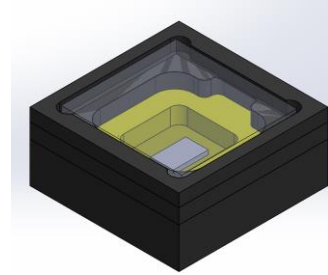


IR light source with high efficiency

VCSEL

SLNF3W35AA



Product Brief

Description

- SMT solderability
- RoHS Compliant
- Low Thermal Resistance
- Pb-free Reflow Soldering application

Features and Benefits

- 3.5mm x 3.5mm x 1.6mm
- SMT package
- Peak wavelength 940 nm
- ESD : HBM 2KV

Key Applications

- Infrared Illumination

Table of Contents

Index

- Product Brief
 - Table of Contents
 - Performance Characteristics
 - Characteristic Diagram
 - Bin Structure
 - Mechanical Dimension
 - Material Structure
 - Packaging Information
 - Reflow Soldering Characteristics
 - Handling of Silicone Resin for VCSELs
 - Precaution For Use
 - Company Information
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Performance Characteristics

Table 1. Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

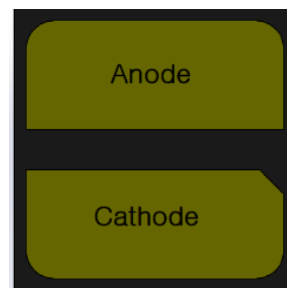
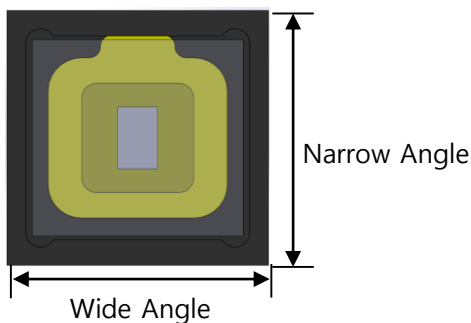
Parameter	Symbol	Value	Unit
Operating Temperature	T_{opr}	0~ +70	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 ~ +85	$^\circ\text{C}$
ESD Sensitivity (HBM)	-	2	KV

Notes :

- (1) Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
- (2) Maximum drive current depends on junction temperature.

Table 2. Electro Optical Characteristics ($I_F = 4\text{A}$, $t_p = 1\text{ms}$, duty =2%, $T_a = 25^\circ\text{C}$)

Parameter	Symbol	Min	Typ.	Max	Unit
Forward Voltage	V_F	-	2.0	-	V
Out Power	P	-	2900	-	mW
Peak wavelength	λ_{peak}	-	940	-	nm
Efficiency	%		36		%
Horizontal FOV	ϕ		60		Deg.
Vertical FOV			45		Deg.


Notes :

All products confirm to the listed minimum and maximum specification for electric and optical characteristics, when operated according to above listed conditions. All production measurements is measured following standardized SSC test environment.

- Tolerance : $I_e/\Phi_e \pm 10\%$, $V_F \pm 0.1\text{V}$, Wavelength $\pm 2\text{nm}$, Viewing angle $\pm 5\text{deg}$.
- Pulse Condition : 1ms @ 25°C

Characteristic Diagram

Fig 1. Relative Spectrum, $T_a = 25^\circ\text{C}$, $I_F = 4\text{A}$, $t_p = 1\text{ms}$, duty =2%

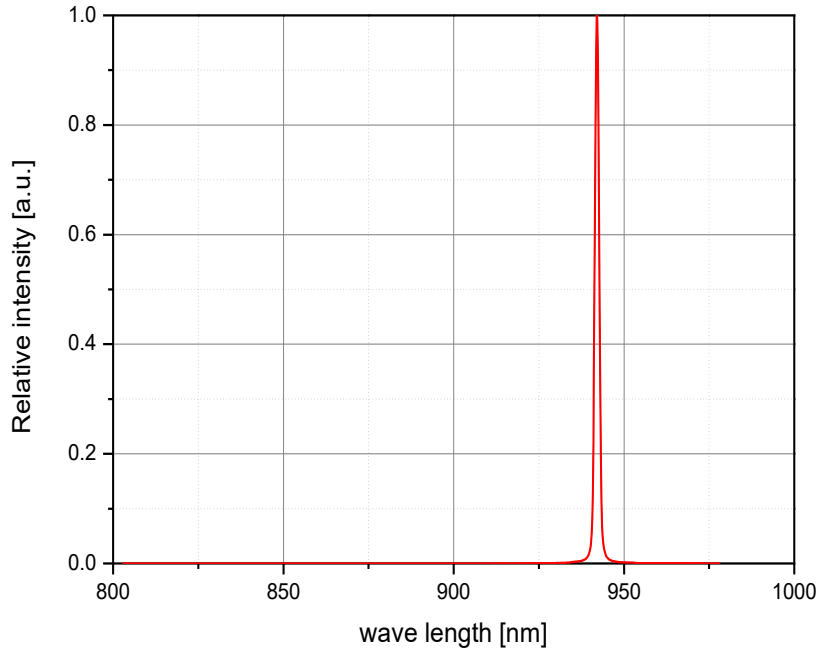
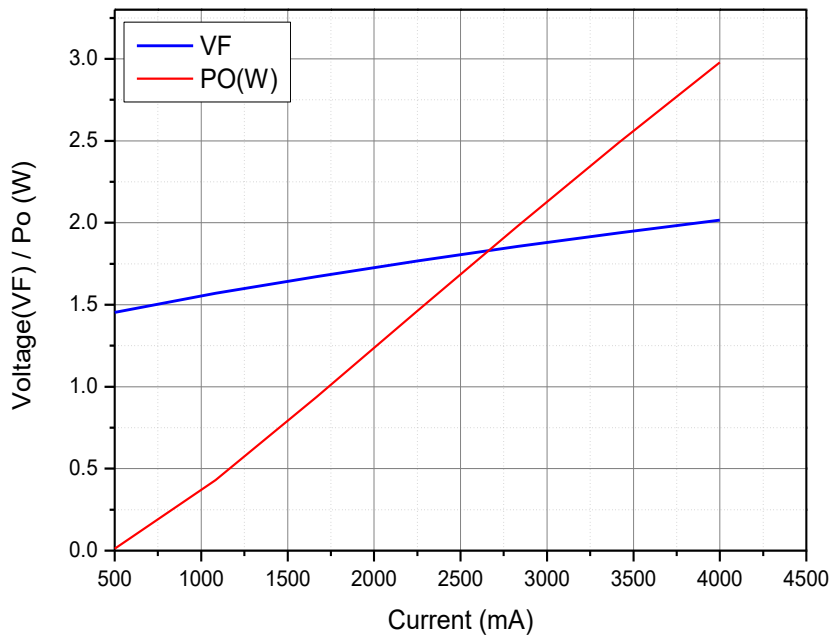


Fig 2. LIV Curve, $T_a = 25^\circ\text{C}$



Bin Structure

Table 5. Bin Code description
Part Number : SLNF3W35AA

Bin Code								
Radiant Intensity			Peak Wavelength			Forward Voltage		
A			A			A		

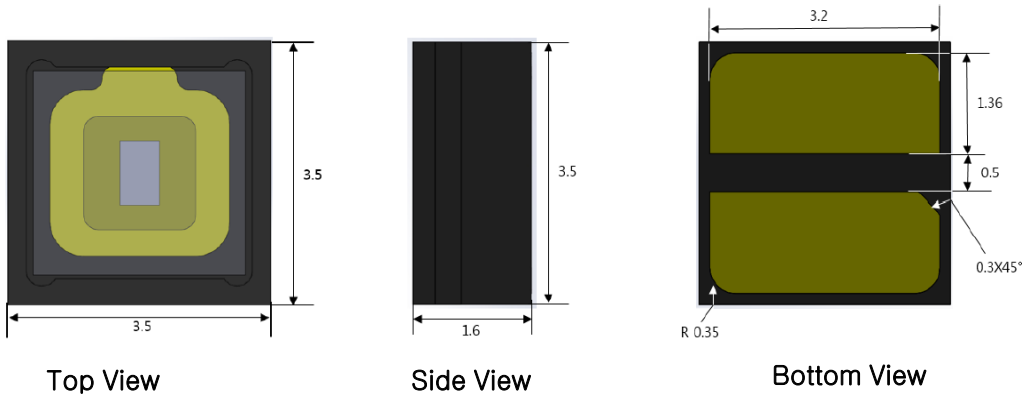
Radiant Intensity (mW) @ I _F = 4A			Peak Wavelength (nm) @ I _F = 4A			Forward Voltage (V) @ I _F = 4A		
Bin Code	Min.	Max.	Bin Code	Min.	Max.	Bin Code	Min.	Max.
A	2000	3500	A	935	950	A	1.5	2.5

Available Ranks

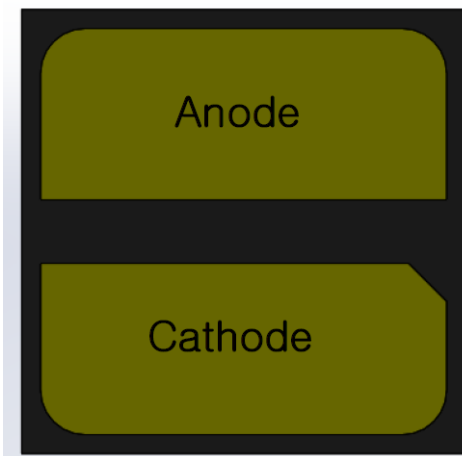
Mechanical Dimensions

(Tolerance: ± 0.1 , Unit: mm)

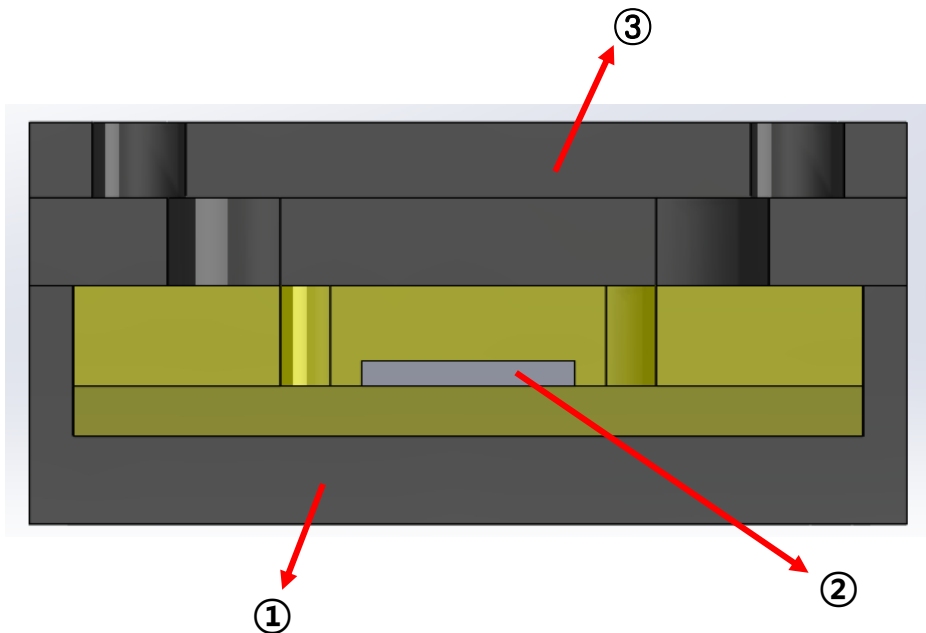
PKG Outline dimension



* Recommend solder pad pattern

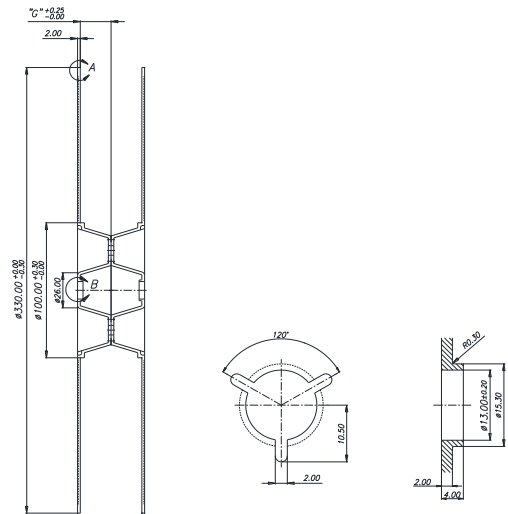
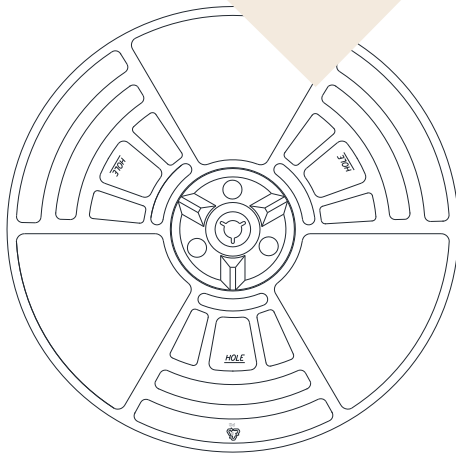
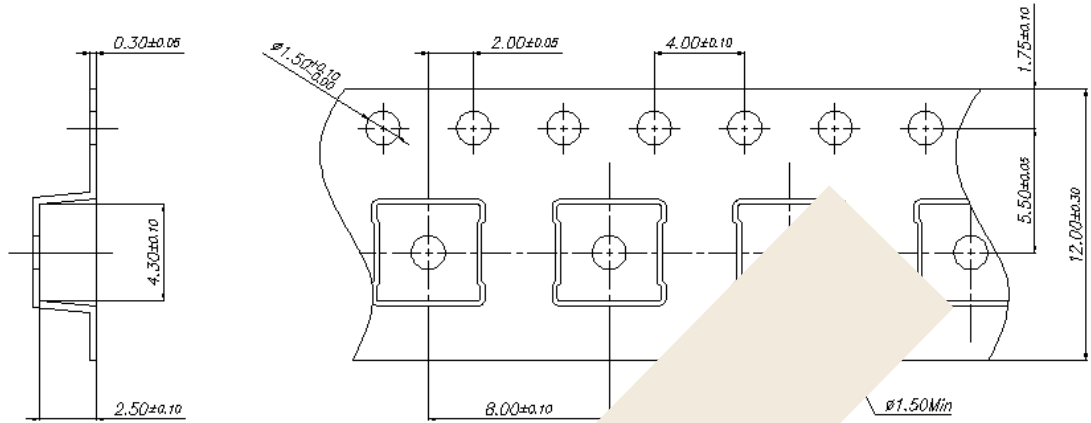


Material Structure



Parts No.	Name	Description	Materials
①	Sub-strate	Metal Ceramic	ALN (Gold Plated)
②	VCSEL	IR VCSEL	
③	diffuser	Lens	Glass + Polymer

Packaging & Label Information

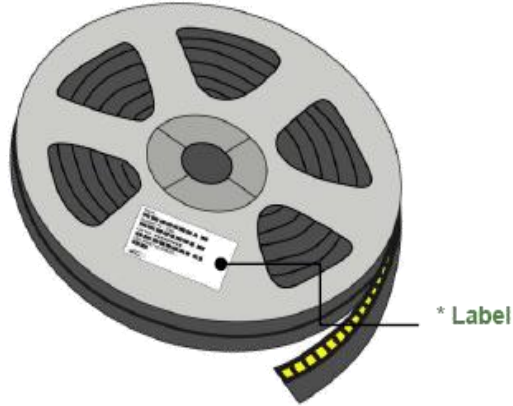


(Tolerance: ± 0.2 , Unit: mm)

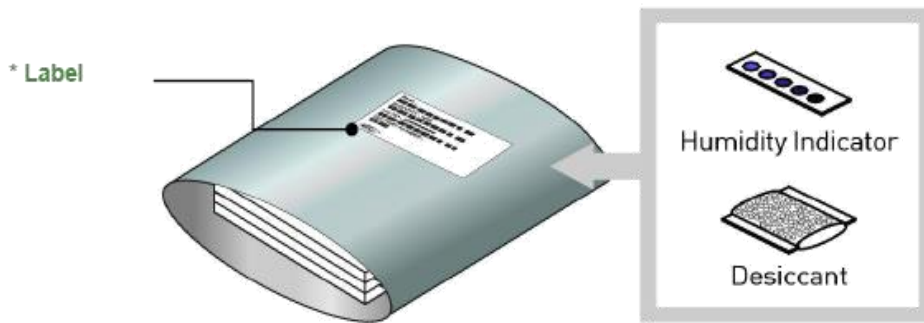
- (1) Quantity : 000pcs/Reel
- (2) Cumulative Tolerance : Cumulative Tolerance/10 pitches to be $\pm 0.2\text{mm}$
- (3) Adhesion Strength of Cover Tape : Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10° to the carrier tape
- (4) Package : P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package

Emitter Tape & Reel Packaging

Reel



Aluminum Bag



Outer Box



Product Nomenclature

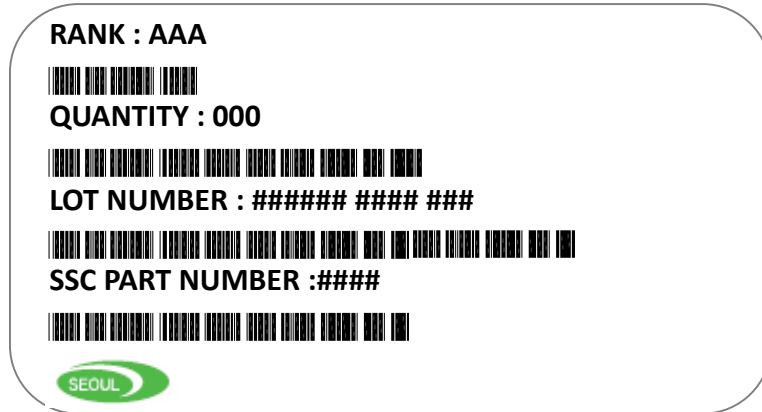


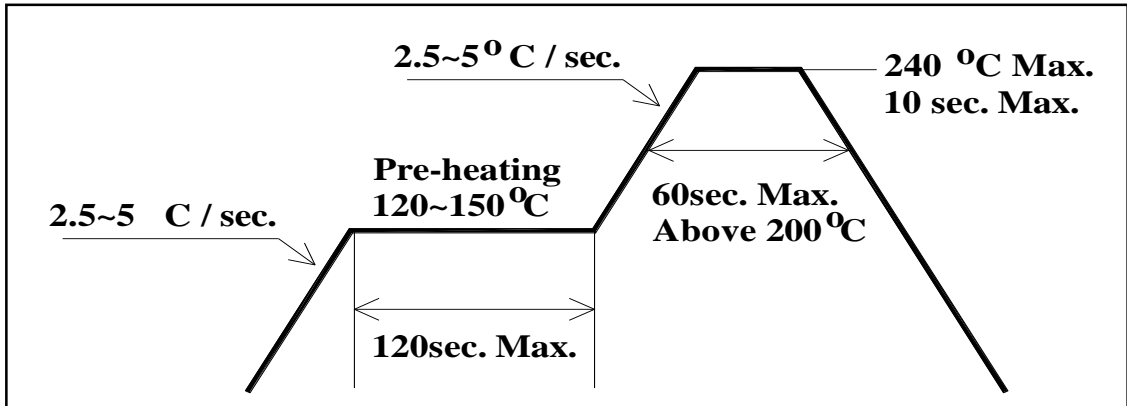
Table 4. Part Numbering System : X₁X₂X₃ - X₄X₅ - X₆X₇ - X₈X₉

The lot number is composed of the following characters aaaaabbbb-ccc-ccc-dddddd

Symbol	Meaning	Example
aaaaa	THE DATE	09A23 (Year : 09, A : Month, 23 : day)
bbbbbb	SSC's Number	Ex) S0017 0001~9999 allowance
ccc-ccc	Order of Taping	014-001
ddddddd	SSC's Number	XXXXXXX

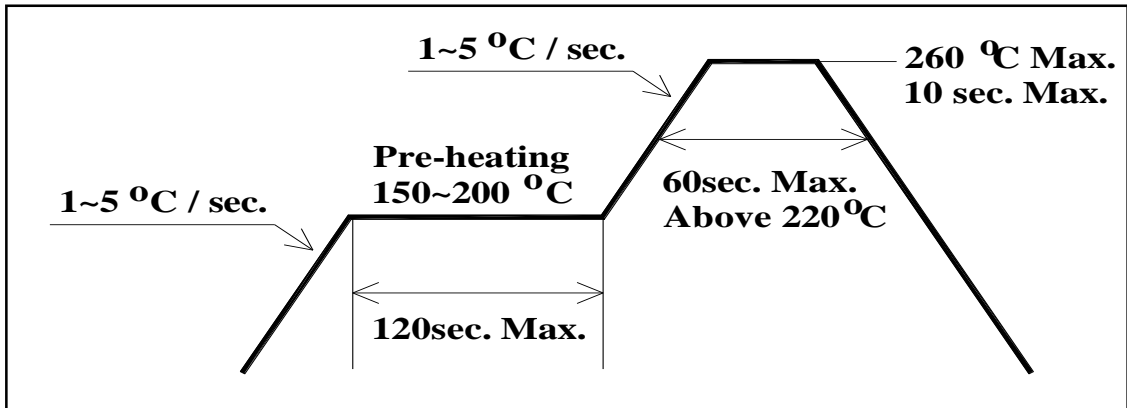
Reflow Soldering Characteristics

(1) Lead Solder



Lead Free Solder	
Pre-heat	120~150°C
Pre-heat time	120 sec. Max.
Peak-Temperature	240°C Max.
Soldering time Condition	10 sec. Max.

(2) Lead-Free Solder



Lead Free Solder	
Pre-heat	150~200°C
Pre-heat time	120 sec. Max.
Peak-Temperature	260°C Max.
Soldering time Condition	10 sec. Max.

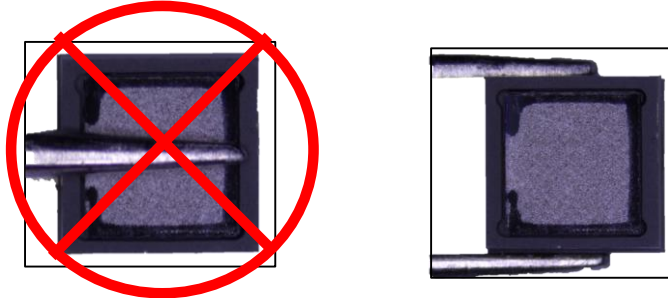
(3) Hand Soldering conditions

Not more than 3 seconds @MAX 350°C, under Soldering iron.

In case that the soldered products are reused in soldering process, we don't guarantee the products.

Handling of Silicone Resin for VCSEL PKG

- (1) During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound.



- (2) In general, VCSEL PKG should only be handled from the side. since the surface can also become scratched.
- (3) When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented. This is assured by choosing a pick and place nozzle which is larger than the VCSEL PKG's reflector area.
- (4) Seoul Semiconductor suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the VCSEL PKG.
- (5) Please do not handle this product with acid or sulfur material in sealed space.
- (6) Avoid leaving fingerprints on silicone resin parts.

Precaution for Use

(1) Storage conditions

Keep the product in a dry box or a desiccator with a desiccant in order to prevent moisture absorption.

a. Keep it at a temperature in the range from 5°C to 30°C and at a humidity of less than 50% RH. The product should be kept within a year.

(2) After opening the package .

When soldering, this could result in a decrease of the photoelectric effect or light intensity.

a. Soldering should be done right after mounting the product.

b. Keep the temperature in the range from 5°C to 30°C and the humidity at less than 60%.

Soldering should be done within 28 days after opening the desiccant package.

If the product has been exposed for more than 28 days after opening the package or the indicating color of the desiccator changes, the product must be baked at a temperature between $65 \pm 5^\circ\text{C}$ for less than 24 hours.

An unused and unsealed product should be repacked in a desiccant package and kept sealed in a dry atmosphere.

Stored at a humidity of less than 10% RH.

(3) Precautions for use

Any external mechanical force or excessive vibration should not be applied to the product during cooling after soldering, and it is preferable to avoid rapid cooling.

The product should not be mounted on a distorted part of PCB.

Gloves or wrist bands for ESD(Electric Static Discharge) should be wore in order to prevent ESD and surge damage, and all devices and equipments must be grounded to the earth.

(4) Miscellaneous

Radiation resistance is not considered.

When cleaning the product, any kind of fluid such as water, oil and organic solvent must not be used and IPA(Isopropyl Alcohol) must be used.

When using the product, operating current should be settled in consideration of the maximum ambient temperature.

Its appearance or specification for improvement is subject to change without notice.

Precaution for Use

(5) LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

Below is a list of suggestions that Seoul Semiconductor purposes to minimize these effects.

a. ESD (Electro Static Discharge)

Electrostatic discharge (ESD) is defined as the release of static electricity when two objects come into contact. While most ESD events are considered harmless, it can be an expensive problem in many industrial environments during production and storage. The damage from ESD to LEDs may cause the product to demonstrate unusual characteristics such as:

- Increase in reverse leakage current lowered turn-on voltage
- Abnormal emissions from the LED at low current

The following recommendations are suggested to help minimize the potential for an ESD event.

One or more recommended work area suggestions:

- Ionizing fan setup
- ESD table/shelf mat made of conductive materials
- ESD safe storage containers

One or more personnel suggestion options:

- Antistatic wrist-strap
- Antistatic material shoes
- Antistatic clothes

Environmental controls:

- Humidity control (ESD gets worse in a dry environment)

Precaution for Use

b. EOS (Electrical Over Stress)

Electrical Over-Stress (EOS) is defined as damage that may occur when an electronic device is subjected to a current or voltage that is beyond the maximum specification limits of the device.

The effects from an EOS event can be noticed through product performance like:

- Changes to the performance of the LED package
(If the damage is around the bond pad area and since the package is completely encapsulated the package may turn on but flicker show severe performance degradation.)
- Changes to the light output of the luminaire from component failure
- Components on the board not operating at determined drive power

Failure of performance from entire fixture due to changes in circuit voltage and current across total circuit causing trickle down failures. It is impossible to predict the failure mode of every LED exposed to electrical overstress as the failure modes have been investigated to vary, but there are some common signs that will indicate an EOS event has occurred:

- Damaged may be noticed to the bond wires (appearing similar to a blown fuse)
- Damage to the bond pads located on the emission surface of the LED package
(shadowing can be noticed around the bond pads while viewing through a microscope)
- Anomalies noticed in the encapsulation and phosphor around the bond wires.
- This damage usually appears due to the thermal stress produced during the EOS event.

c. To help minimize the damage from an EOS event Seoul Semiconductor recommends utilizing:

- A surge protection circuit
- An appropriately rated over voltage protection device
- A current limiting device



Company Information

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Company Information

Seoul Semiconductor (www.SeoulSemicon.com) manufactures and packages a wide selection of light emitting diodes (LEDs) for the automotive, general illumination/lighting, Home appliance, signage and back lighting markets. The company is the world's fifth largest LED supplier, holding more than 10,000 patents globally, while offering a wide range of LED technology and production capacity in areas such as "nPola", "Acrich", the world's first commercially produced AC LED, and "Acrich MJT - Multi-Junction Technology" a proprietary family of high-voltage LEDs.

The company's broad product portfolio includes a wide array of package and device choices such as Acrich and Acirch2, high-brightness LEDs, mid-power LEDs, side-view LEDs, and through-hole type LEDs as well as custom modules, displays, and sensors.

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